

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant: Akira CHINDA et al.

Title: WIRING BOARD, SEMICONDUCTOR DEVICE, AND  
PROCESS FOR PRODUCTION OF WIRING BOARD

Appl. No.: Unassigned

Filing Date: December 19, 2001

Examiner: Unassigned

Art Unit: Unassigned

8/1/02  
04/9  
5-3-02

**PRELIMINARY AMENDMENT**

Commissioner for Patents  
Washington, D.C. 20231

Sir:

Prior to examination of the present Application, Applicants respectfully request that the above-identified application be amended as follows:

**IN THE CLAIMS:**

In accordance with 37 CFR § 1.121, please substitute for original claim 2, the following rewritten version of the same claim, as amended, and please renumber claims 40 - 43 (1<sup>st</sup> Claim 43) as claims 39-42 as shown below. The changes are shown explicitly in the attached "Versions With Markings to Show Changes Made."

91 2. (Amended) A wiring board as claimed in claim 1, wherein:  
a thickness of said conductive member is  $\frac{1}{2}$  or more of that of said insulating substrate.

92 39. (Amended) A process for the production of a wiring board as claimed in claim 37, wherein:  
a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.

40. (Amended) A process for the production of a wiring board as claimed in claim 38, wherein:  
a step for forming said conductive member is effected by forming a copper (Cu) plating or a nickel (Ni) plating in accordance with electroplating method.